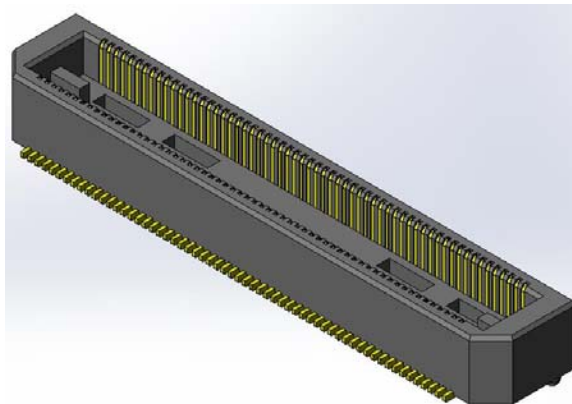


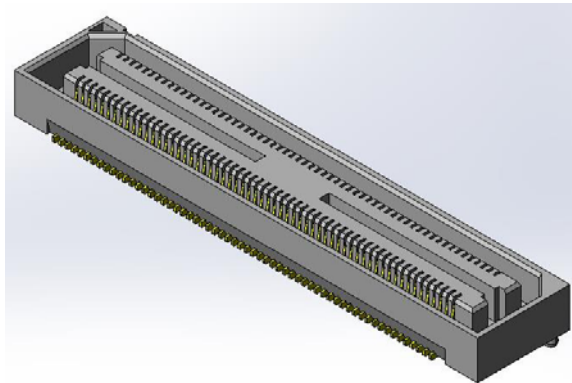


High Speed Characterization Report

BTH-060-01-F-D-A



BSH-060-01-F-D-A



Description:

**Basic Blade & Beam Header and Socket, Extended Life Product™
0.5mm (.0197") Pitch, 5mm (.197") Stack Height**

Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

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Connector Overview

Samtec's BTH/BSH Basic Blade & Beam Header and Socket are designed for high-speed board-to-board applications where signal integrity is essential. BTH/BSH is a double row contacts system available with up to 300 I/Os in stack height of 5,00 mm (.197") and other heights available as application specific. The data in this report is applicable only to a 5mm stack height.

Connector System Speed Rating

BTH/BSH Series Basic Blade & Beam Header and Socket, 0.5mm (.0197") Pitch, 5mm (0.197") Stack Height

<u>Signaling</u>	<u>Speed Rating</u>
Single-Ended:	9.0 GHz/ 18 Gbps
Differential:	9.5 GHz/ 19 Gbps

The Speed Rating is based on the -3 dB insertion loss point of the connector system. The -3 dB point can be used to estimate usable system bandwidth in a typical, two-level signaling environment.

To calculate the Speed Rating, the measured -3 dB point is rounded-up to the nearest half-GHz level. The up rounding corrects for a portion of the test board's trace loss, since a short length of trace loss included in the loss data in this report. The resulting loss value is then doubled to determine the approximate maximum data rate in Gigabits per second (Gbps).

For example, a connector with a -3 dB point of 7.8 GHz would have a Speed Rating of 8 GHz/ 16 Gbps. A connector with a -3 dB point of 7.2 GHz would have a Speed Rating of 7.5 GHz/ 15 Gbps.

Series: Basic Blade & Beam Header and Socket, Extended Life Product™

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Frequency Domain Data Summary

Table 1 - Single-Ended Connector System Performance				
Test Parameter	Configuration	Driver	Receiver	
Insertion Loss	GSG	BTH_98	BSH_98	3dB @ 9.0 GHz
Return Loss	GSG	BTH_98	BTH_98	>10dB to 6.5 GHz
Near-End Crosstalk	GAQG	BTH_28	BTH_30	< -20dB to 0.7 GHz
	GAGQG	BTH_98	BTH_102	< -20dB to 9.0 GHz
	Xrow, GAG to GQG	BTH_97	BTH_98	< -20dB to 20.0 GHz
Far-End Crosstalk	GAQG	BTH_28	BTH_30	< -20dB to 9.5 GHz
	GAGQG	BTH_98	BTH_102	< -20dB to 9.5 GHz
	Xrow, GAG to GQG	BTH_97	BTH_98	< -20dB to 20.0 GHz

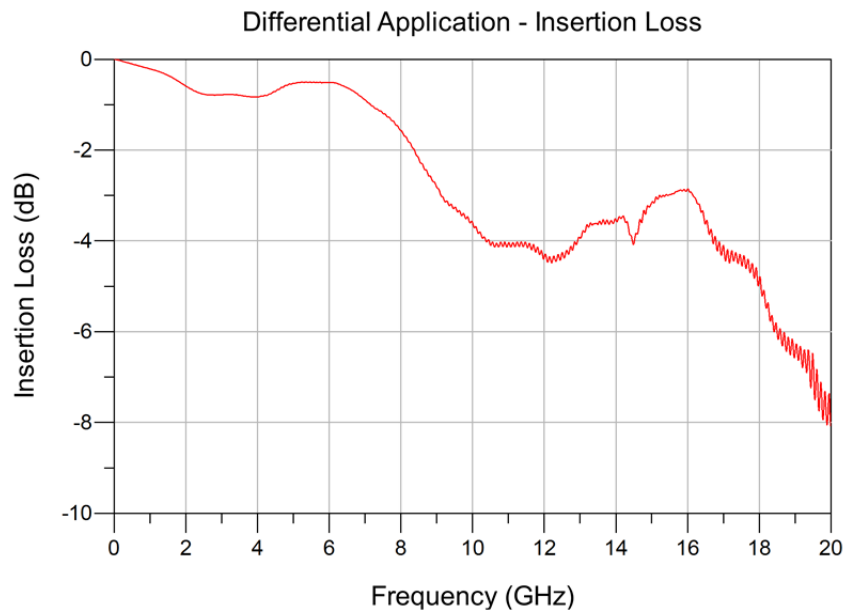
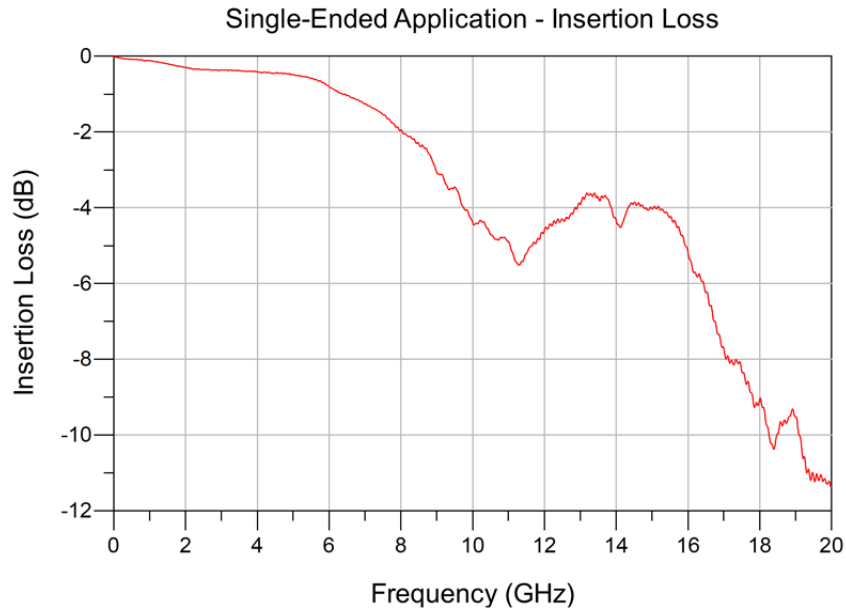
Table 2 - Differential Connector System Performance				
Test Parameter	Configuration	Driver	Receiver	
Insertion Loss	GSSG	BTH_63,65	BTH_63,65	3dB @ 9.1 GHz
Return Loss	GSSG	BTH_63,65	BTH_63,65	>10dB to 2.0 GHz
Near-End Crosstalk	GAAQQG	BTH_57,59	BTH_61,63	< -20dB to 13.2 GHz
	GAAGQQG	BTH_57,59	BTH_63,65	< -20dB to 20.0 GHz
	Xrow, GAAG to GQQG	BTH_27,29	BTH_28,30	< -20dB to 20.0 GHz
Far-End Crosstalk	GAAQQG	BTH_57,59	BTH_61,63	< -20dB to 20.0 GHz
	GAAGQQG	BTH_57,59	BTH_63,65	< -20dB to 20.0 GHz
	Xrow, GAAG to GQQG	BTH_27,29	BTH_28,30	< -20dB to 20.0 GHz

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Bandwidth Chart – Single-Ended & Differential Insertion Loss

BTH/BSH Connector Series



Series: Basic Blade & Beam Header and Socket, Extended Life Product™

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Time Domain Data Summary

Table 3 - Single-Ended Impedance (Ω)					
Signal Risetime	30ps	50ps	100ps	250ps	500ps
Maximum Impedance	49.93	49.85	49.71	49.44	49.13
Minimum Impedance	41.41	42.66	44.94	46.33	47.49

Single-Ended Application - Impedance vs. Risetime

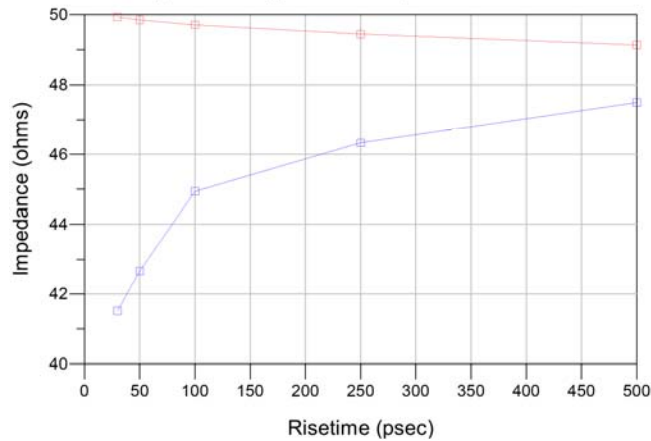
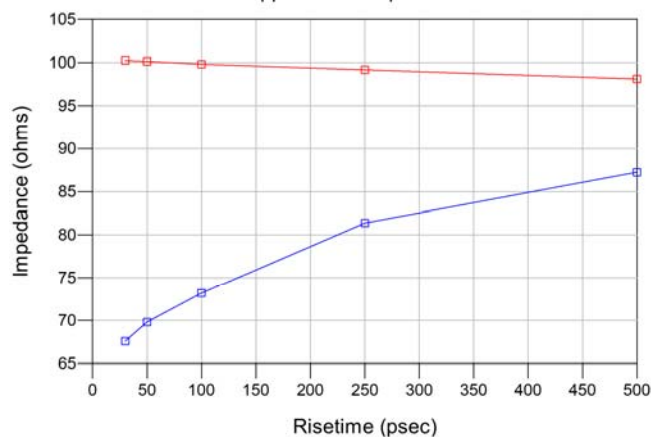


Table 4 - Differential Impedance (Ω)					
Signal Risetime	30ps	50ps	100ps	250ps	500ps
Maximum Impedance	100.25	100.15	99.83	99.19	98.12
Minimum Impedance	67.59	69.81	73.21	81.37	87.24

Differential Application - Impedance vs. Risetime



Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Table 5 - Single-Ended Crosstalk (%)

Input(tr)		Driver	Receiver	30ps	50ps	100ps	250ps	500ps
NEXT	GAQG	BTH_28	BTH_30	21.02	17.84	15.02	7.99	4.51
	GAGQG	BTH_98	BTH_102	4.22	2.95	2.14	1.19	0.63
	Xrow	BTH_97	BTH_98	0.63	0.48	0.34	0.15	<0.1
FEXT	GAQG	BTH_28	BTH_30	2.84	2.07	1.25	0.35	0.12
	GAGQG	BTH_98	BTH_102	3.15	2.50	1.34	0.45	0.25
	Xrow	BTH_97	BTH_98	0.61	0.42	0.22	<0.1	<0.1

Table 6 - Differential Crosstalk (%)

Input(tr)		Driver	Receiver	30ps	50ps	100ps	250ps	500ps
NEXT	GAAQQG	BTH_57,59	BTH_61,63	5.78	4.94	4.18	2.71	1.55
	GAAGQQG	BTH_57,59	BTH_63,65	0.59	0.37	0.21	<0.1	<0.1
	Xrow	BTH_27,29	BTH_28,30	<0.1	<0.1	<0.1	<0.1	<0.1
FEXT	GAAQQG	BTH_57,59	BTH_61,63	2.01	1.65	1.44	0.90	0.49
	GAAGQQG	BTH_57,59	BTH_63,65	0.75	0.52	0.26	<0.1	<0.1
	Xrow	BTH_27,29	BTH_28,30	<0.1	<0.1	<0.1	<0.1	<0.1

Table 7 - Propagation Delay (Mated Connector)

Single-Ended	61 ps
Differential	57 ps

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Characterization Details

This report presents data that characterizes the signal integrity response of a connector pair in a controlled printed circuit board (PCB) environment. All efforts are made to reveal typical best-case responses inherent to the system under test (SUT).

In this report, the SUT includes the connector pair and footprint effects on a typical multi-layer PCB. PCB effects (trace loss) are de-embedded from test data. Board related effects, such as pad-to-ground capacitance, are included in the data presented in this report.

Additionally, intermediate test signal connections can mask the connector's true performance. Such connection effects are minimized by using high performance test cables and adapters. Where appropriate, calibration and de-embedding routines are also used to reduce residual effects.

Differential and Single-Ended Data

Most Samtec connectors can be used successfully in both differential and single-ended applications. However, electrical performance will differ depending on the signal drive type. In this report, data is presented for both differentially and single-ended driven scenarios.

Connector Signal to Ground Ratio

Samtec connectors are most often designed for generic applications and can be implemented using various signal and ground pin assignments. In high speed systems, provisions must be made in the interconnect for signal return currents. Such paths are often referred to as "ground". In some connectors, a ground plane or blade, or an outer shield, is used as the signal return, while in others, connector pins are used as signal returns. Various combinations of signal pins, ground blades, and shields can also be utilized. Electrical performance can vary significantly depending upon the number and location of ground pins.

In general, the more pins dedicated to ground, the better electrical performance will be. However, dedicating pins to ground reduces signal density of a connector. Therefore, care must be taken when choosing signal/ground ratios in cost or density-sensitive applications.

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For this connector, the following configurations were evaluated:

Single-Ended Impedance:

- GSG (Ground-Signal-Ground)

Single-Ended Crosstalk:

- Electrical "worst case": GAQG (Ground-Active-Quiet-Ground)
- Electrical "best case": GAGQG (Ground-Active-Ground-Quiet-Ground)
- Across row: "xrow case": GAG to GQG (from one row of terminals to the other row)

Differential Impedance:

- GSSG (Ground-positive Signal-negative Signal-Ground)

Differential Crosstalk:

- Electrical "worst case": GAAQQG (Ground-Active-Active-Quiet-Quiet-Ground)
- Electrical "best case": GAAGQQG (Ground-Active-Active-Ground-Quiet-Quiet-Ground)
- Across row: "xrow case": GAAG to GQQG (from one row of terminals to the other row)

Only one single-ended signal or differential pair was driven for crosstalk measurements.

Other configurations can be evaluated upon request. Please contact sig@samtec.com for more information.

In a real system environment, active signals might be located at the outer edges of the signal contacts of concern, as opposed to the ground signals utilized in laboratory testing. For example, in a single-ended system, a pin-out of "SSSS", or four adjacent single ended signals might be encountered as opposed to the "GSG" and "GSSG" configurations tested in the laboratory. Electrical characteristics in such applications could vary slightly from laboratory results. However, in most applications, performance can safely be considered equivalent.

Signal Edge Speed (Rise Time):

In pulse signaling applications, the perceived performance of the interconnect can vary significantly depending on the edge rate or rise time of the exciting signal. For this report, the fastest rise time used was 30 ps. Generally, this should demonstrate worst-case performance.

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In many systems, the signal edge rate will be significantly slower at the connector than at the driver launch point. To estimate interconnect performance at other edge rates, data is provided for several rise times between 30ps and 500ps.

For this report, measured rise times were at 10%-90% signal levels.

Frequency Domain Data

Frequency Domain parameters are helpful in evaluating the connector system's signal loss and crosstalk characteristics across a range of sinusoidal frequencies. In this report, parameters presented in the Frequency Domain are Insertion Loss, Return Loss, and Near-End and Far-End Crosstalk. Other parameters or formats, such as VSWR or S-Parameters, may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

Frequency performance characteristics for the SUT are generated directly from network analyzer measurements.

Time Domain Data

Time Domain parameters indicate Impedance mismatch versus length, signal propagation time and crosstalk in a pulsed signal environment.

Impedance mismatch versus length is measured by DSA8200 Digital Serial Analyzer. Board related effects, such as pad-to-ground capacitance and trace loss, are included in the data presented in this report. The impedance data is provided in [Appendix E](#) of this report.

The measured S-Parameters from the network analyzer are post-processed using Agilent Advanced Design System to obtain the time domain response for signal propagation time and crosstalk. The Time Domain procedure is provided in [Appendix E](#) of this report. Parameters or formats not included in this report may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

In this report, propagation delay is defined as the signal propagation time through the connector and connector footprint. It includes 10 mils of PCB trace on the both BTH and BSH connector side. Delay is measured at 30 picoseconds signal risetime. Delay is calculated as the difference in time measured between the 50% amplitude levels of the input and output pulses.

Crosstalk or coupled noise data is provided for various signal configurations. All measurements are single disturber. Crosstalk is calculated as a ratio of the input line voltage to the coupled line voltage. The input line is sometimes described as the active or drive

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line. The coupled line is sometimes described as the quiet or victim line. Crosstalk ratio is tabulated in this report as a percentage. Measurements are made at both the near-end and far-end of the SUT.

Data for other configurations may be available. Please contact our Signal Integrity Group at sig@samtec.com for further information.

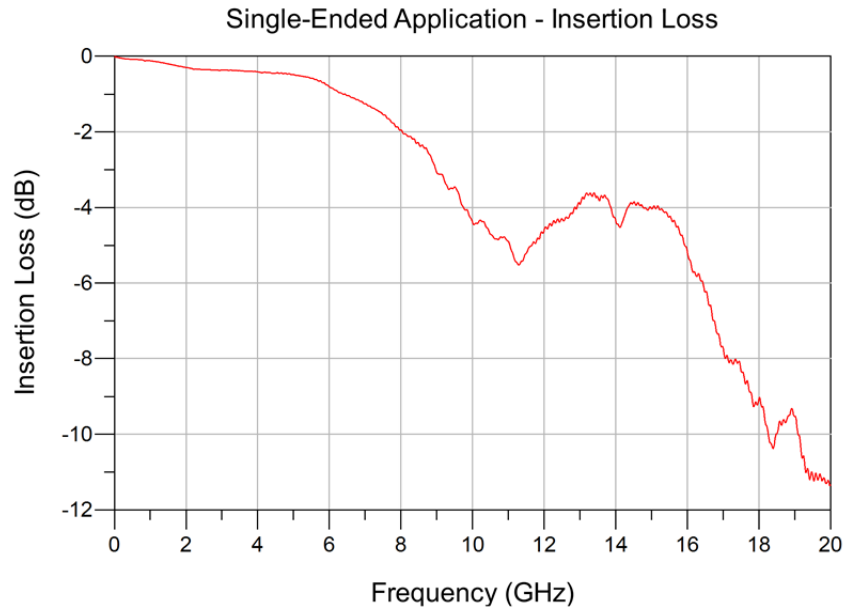
As a rule of thumb, 10% crosstalk levels are often used as a general first pass limit for determining acceptable interconnect performance. However, modern system crosstalk tolerance can vary greatly. For advice on connector suitability for specific applications, please contact our Signal Integrity Group at sig@samtec.com.

Additional information concerning test conditions and procedures is located in the appendices of this report. Further information may be obtained by contacting our Signal Integrity Group at sig@samtec.com.

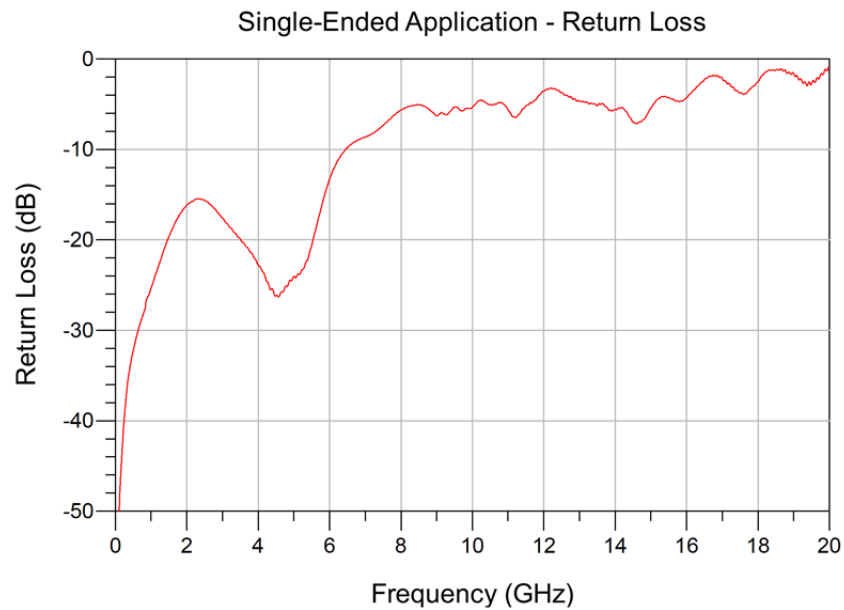
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Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Appendix A – Frequency Domain Response Graphs

Single-Ended Application – Insertion Loss



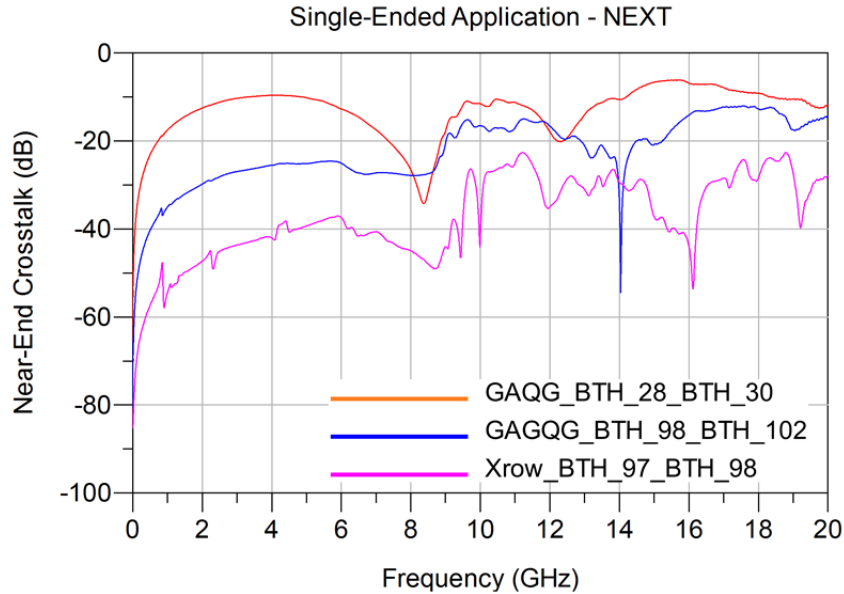
Single-Ended Application – Return Loss



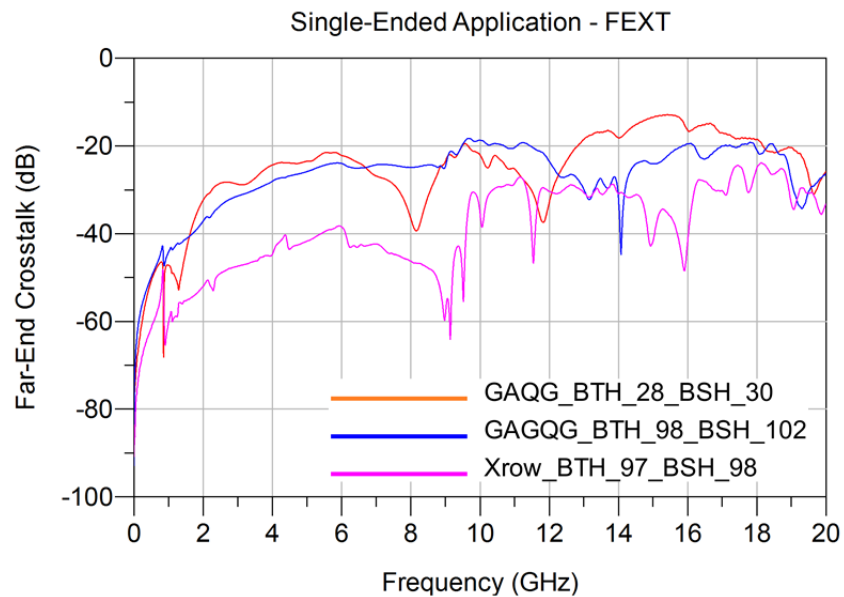
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Single-Ended Application – NEXT Configurations



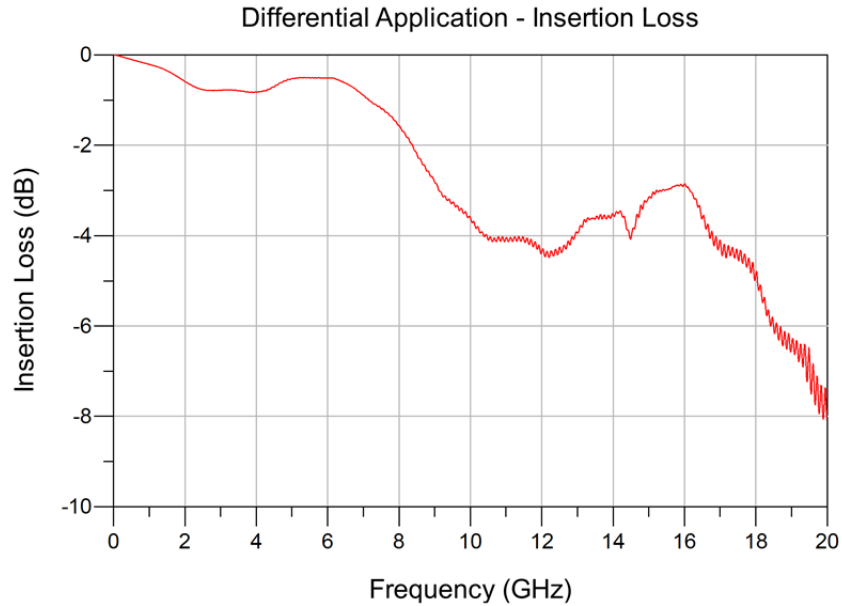
Single-Ended Application – FEXT Configurations



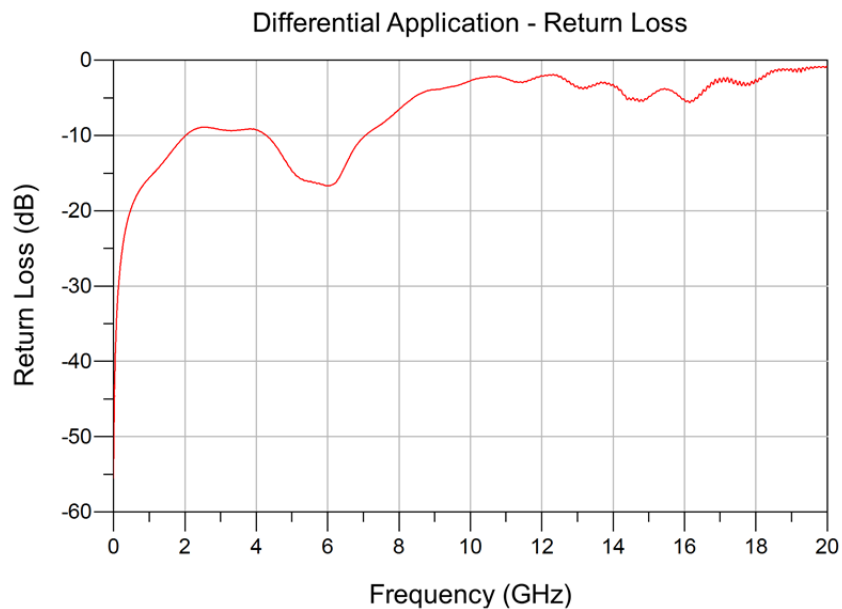
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Differential Application – Insertion Loss

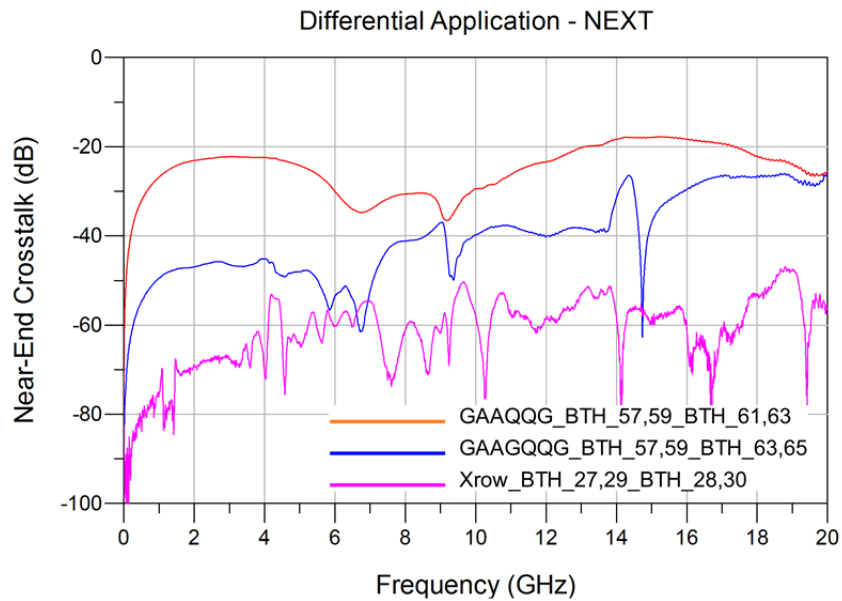


Differential Application – Return Loss

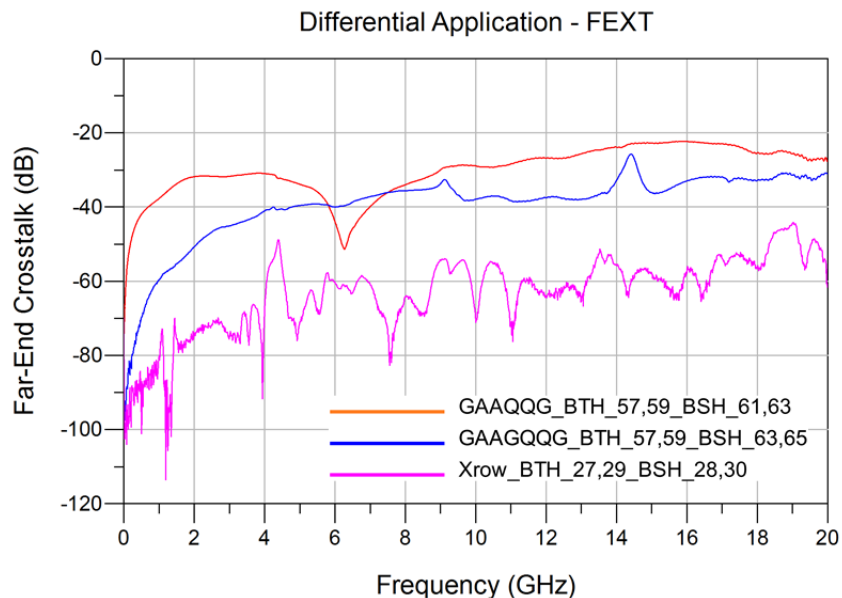


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Differential Application – NEXT Configurations



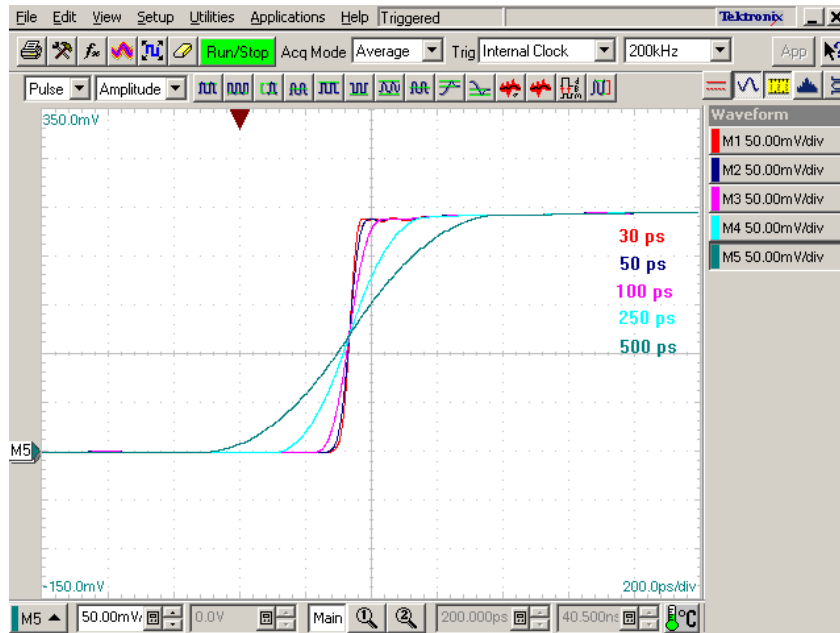
Differential Application – FEXT Configurations



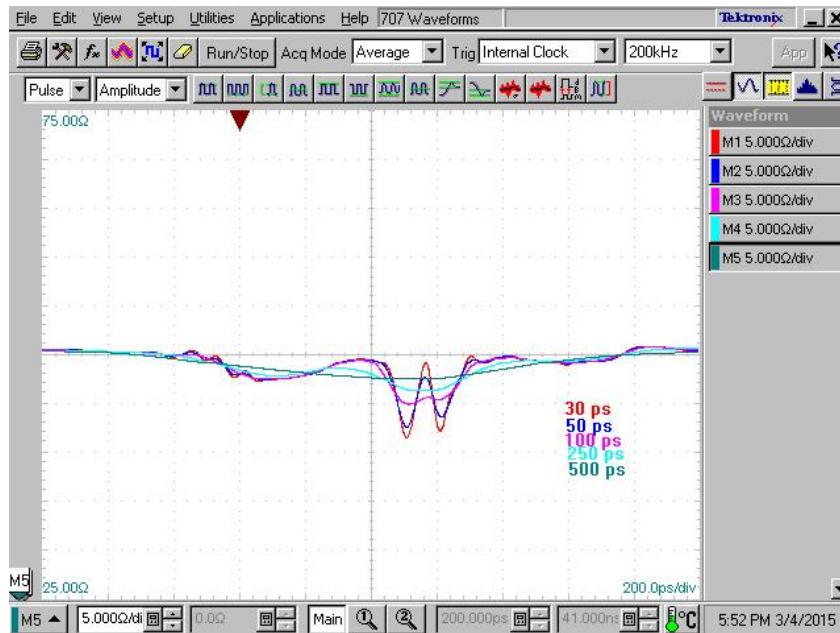
Series: Basic Blade & Beam Header and Socket, Extended Life Product™
Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Appendix B – Time Domain Response Graphs

Single-Ended Application – Input Pulse

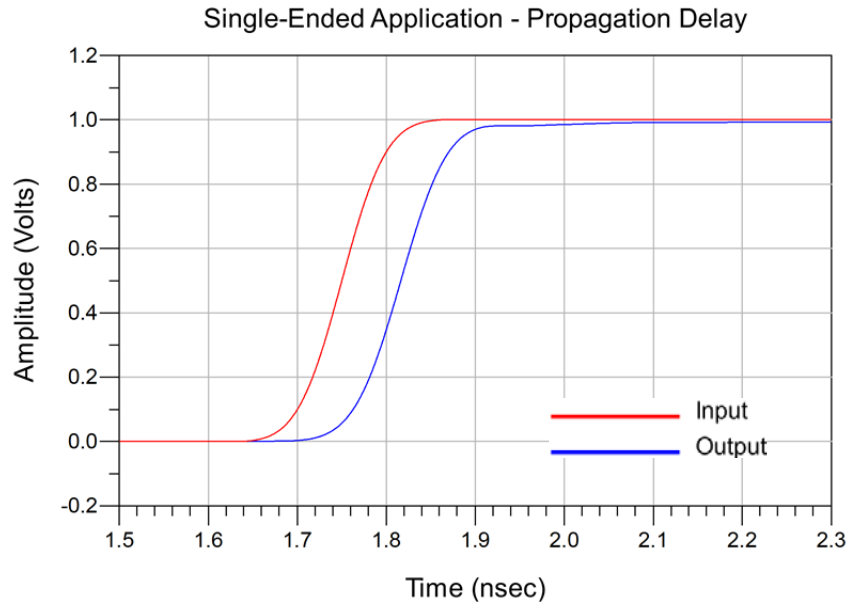


Single-Ended Application – Impedance

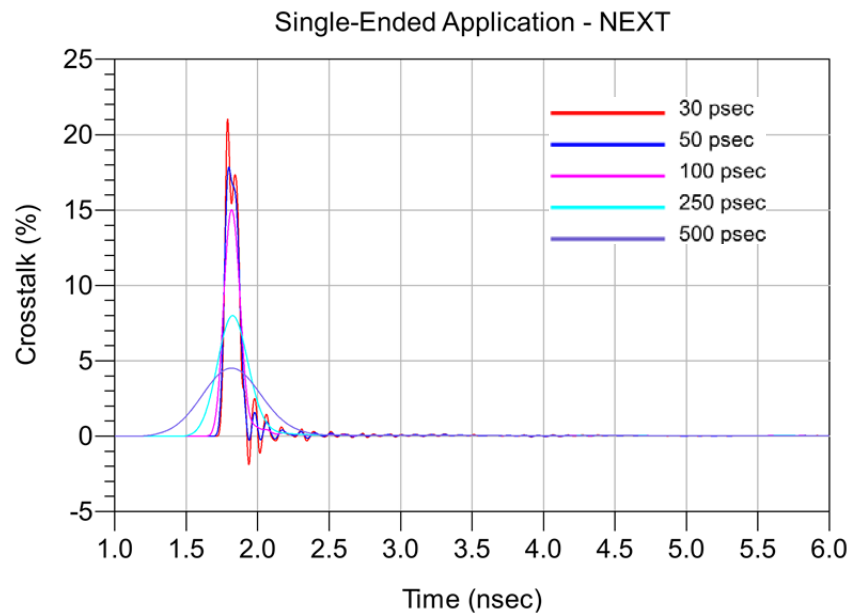


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Single-Ended Application – Propagation Delay

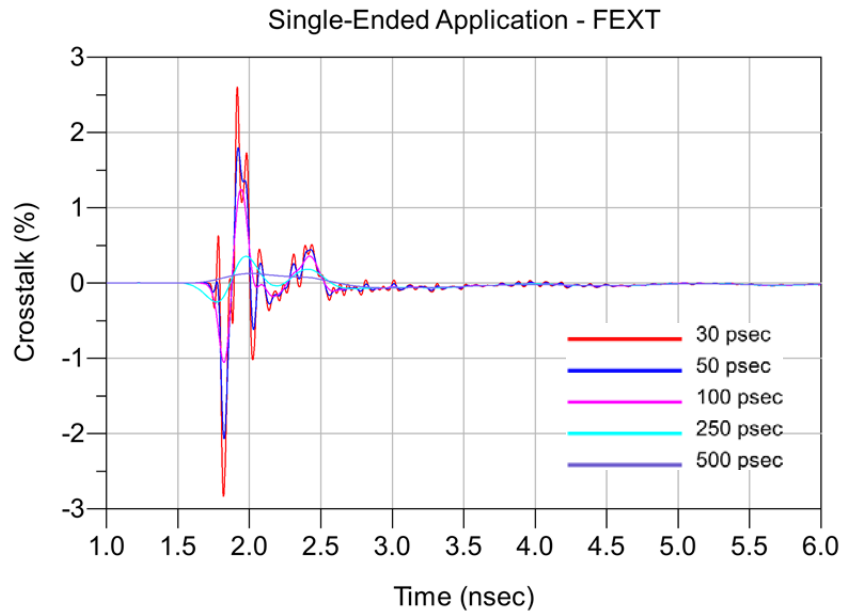


Single-Ended Application – NEXT, Worst Case Configuration, BTH_28_BTH_30

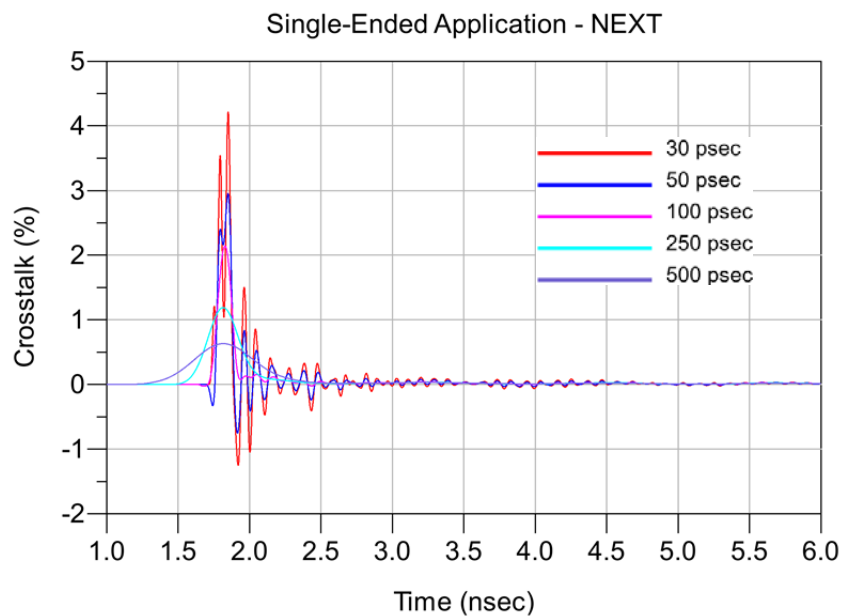


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Single-Ended Application – FEXT, Worst Case Configuration, BTH_28_BSH_30



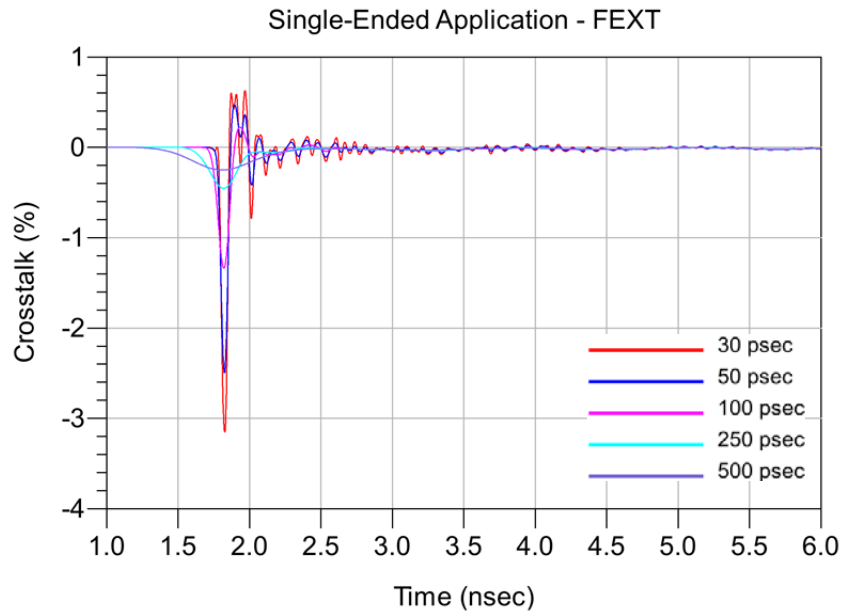
Single-Ended Application – NEXT, Best Case Configuration, BTH_98_BTH_102



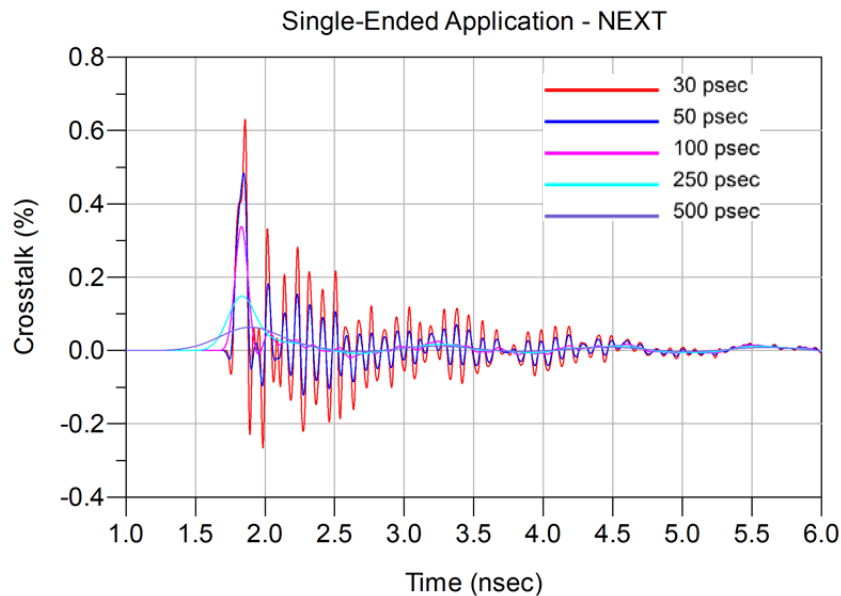
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Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Single-Ended Application – FEXT, Best Case Configuration, BTH_98_BSH_102



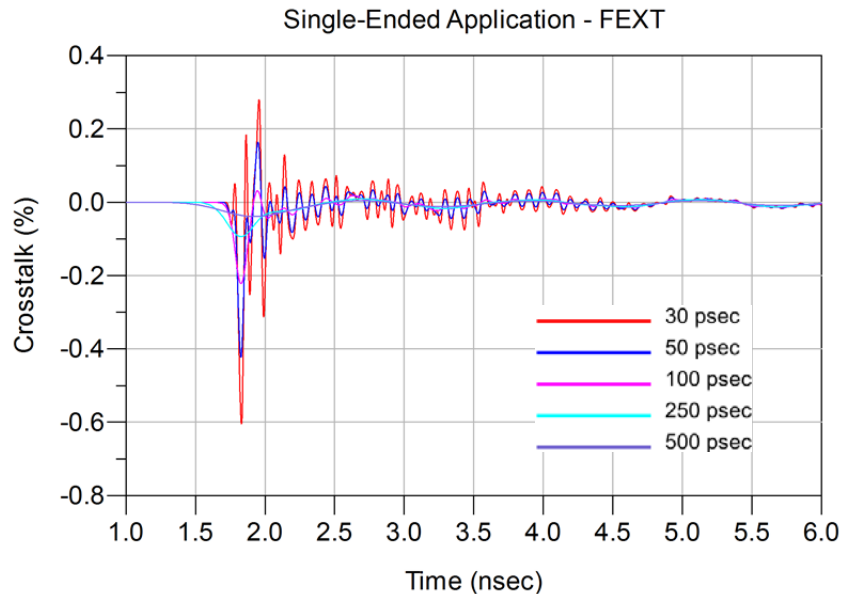
Single-Ended Application – NEXT, Across Row Configuration, BTH_97_BTH_98



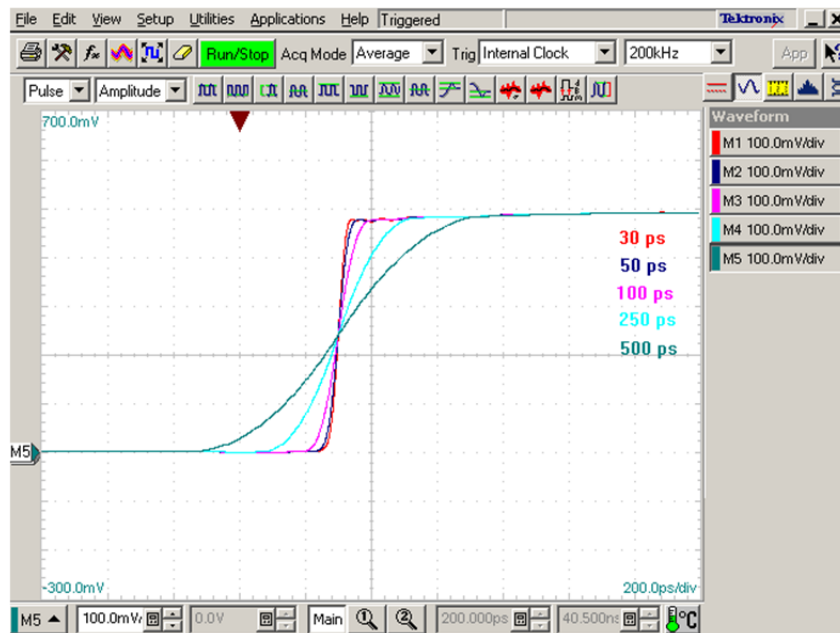
Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Single-Ended Application – FEXT, Across Row Configuration, BTH_97_BSH_98

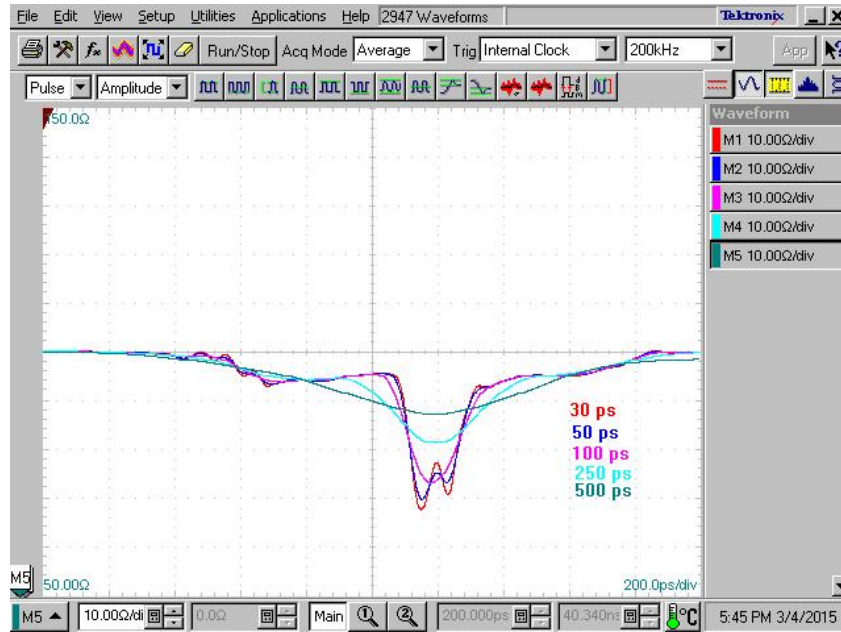


Differential Application – Input Pulse

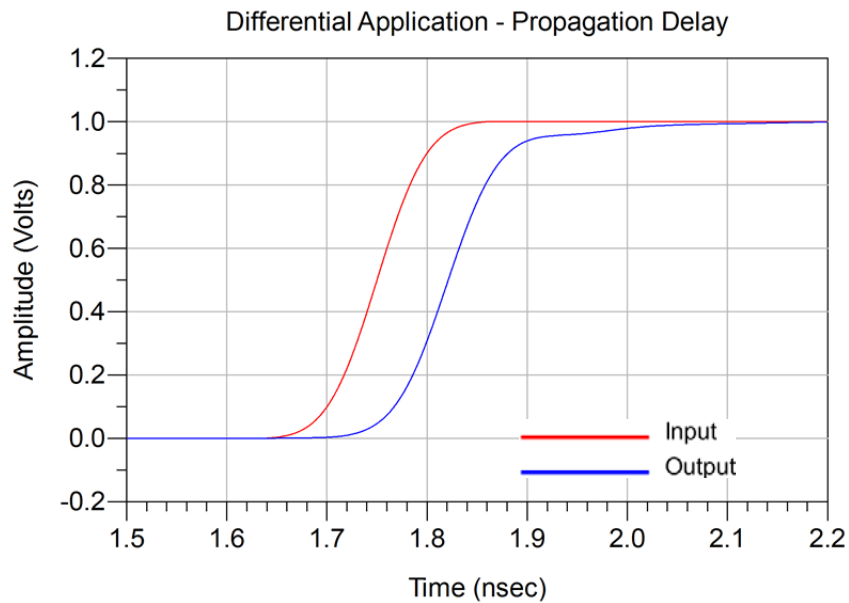


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Differential Application – Impedance



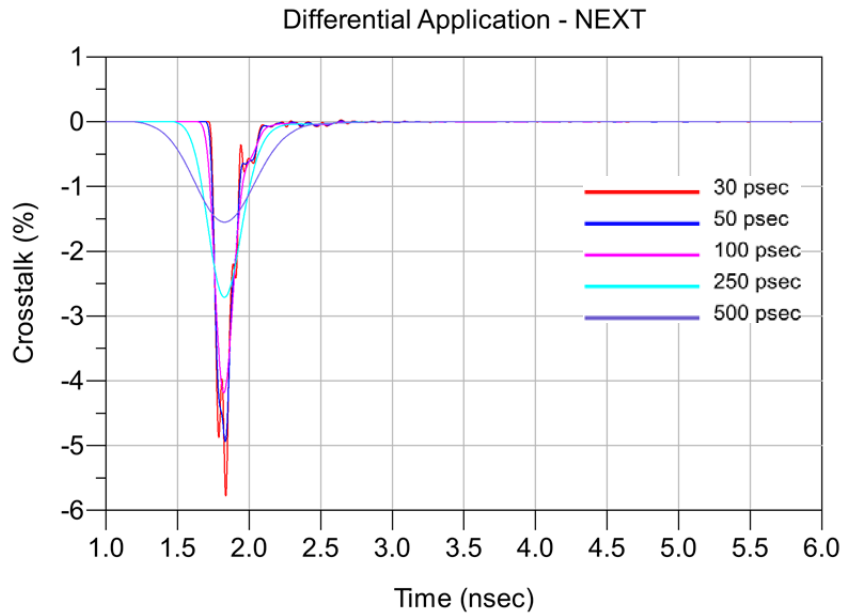
Differential Application – Propagation Delay



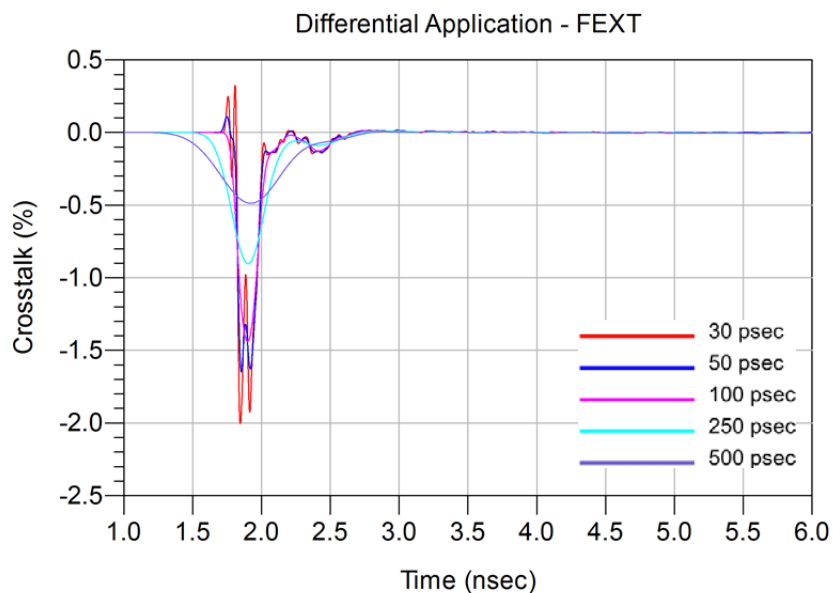
Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Differential Application – NEXT, Worst Case Configuration, BTH_57,59_BTH_61,63



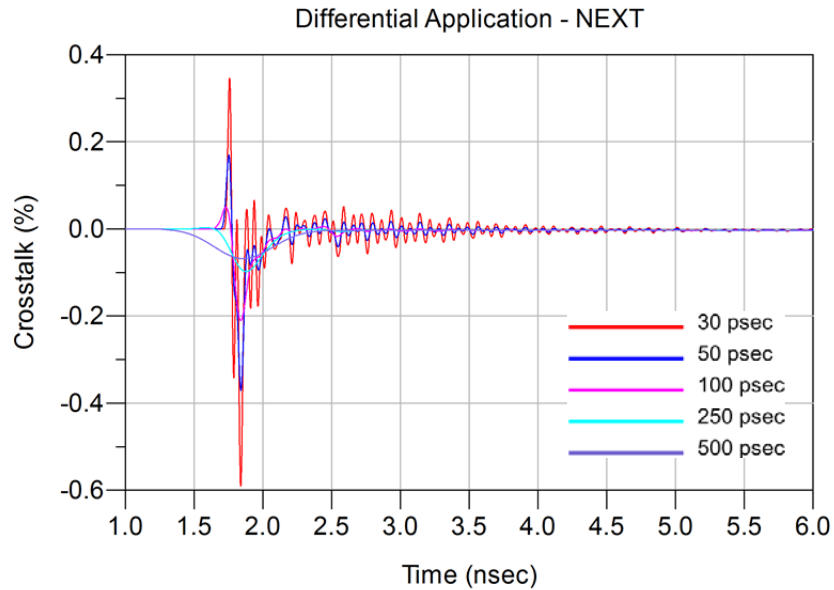
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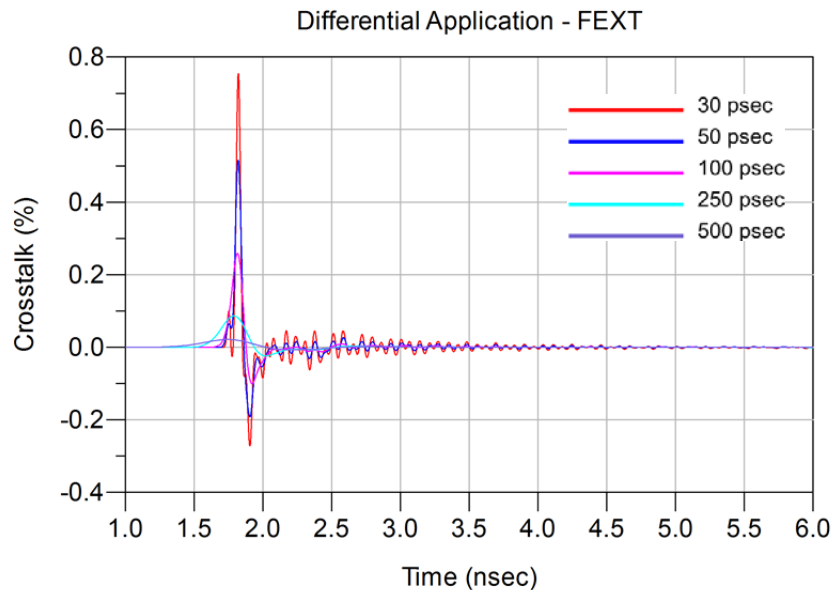
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Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Differential Application – NEXT, Best Case Configuration, BTH_57,59_BTH_63,65



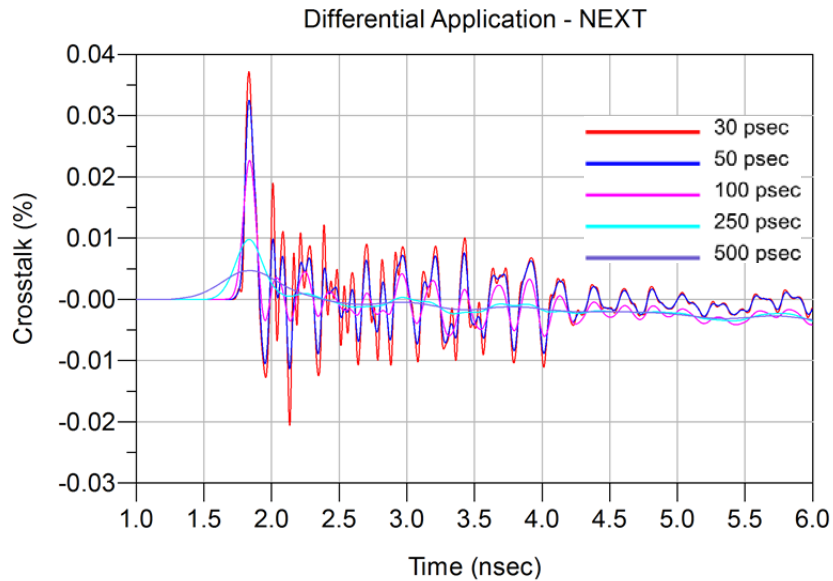
Differential Application – FEXT, Best Case Configuration, BTH_57,59_BSH_63,65



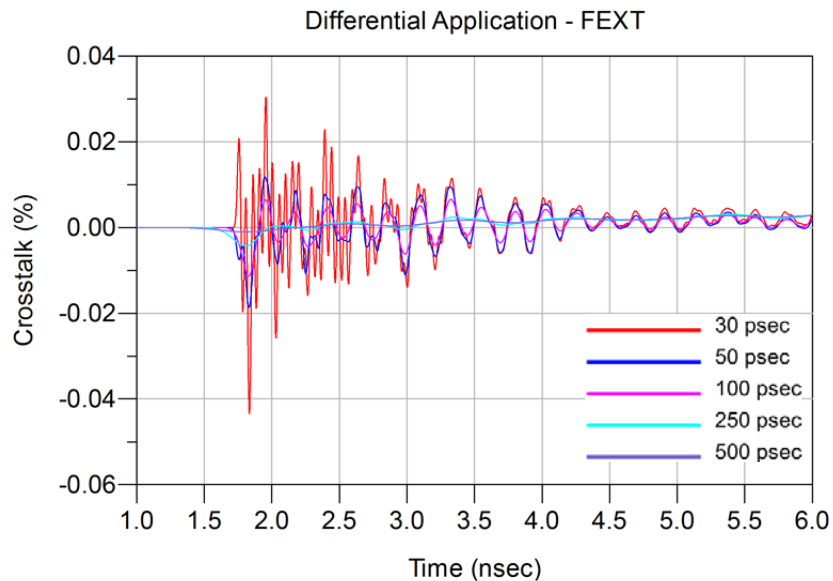
Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

**Differential Application – NEXT, Across Row Case Configuration,
BTH_27,29_BTH_28,30**



**Differential Application – FEXT, Across Row Case Configuration,
BTH_27,29_BSH_28,30**



Series: Basic Blade & Beam Header and Socket, Extended Life Product™
Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Appendix C – Product and Test System Descriptions

Product Description

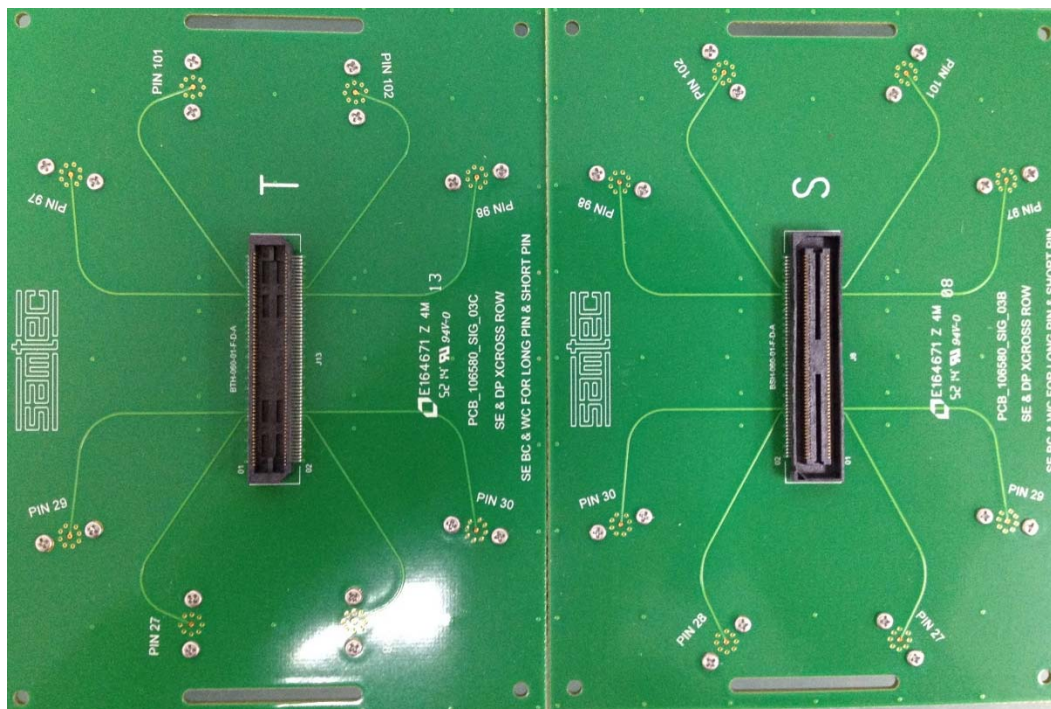
Product test samples are BTH/BSH Basic Blade & Beam Header and Socket. The part number is BTH-060-01-F-D-A and it mates to BSH-060-01-F-D-A. The connector has two rows of 60 contacts evenly spaced on a 0.5 mm (0.0197") pitch. A photo of the test articles mounted to SI test boards is shown below.

Test System Description

The test fixtures are composed of four-layer FR-4 material with 50Ω signal trace and pad configurations designed for the electrical characterization of Samtec high speed connector products. A PCB mount SMA connector is used to interface the test cables to test fixtures. Optimization of the SMA launch was performed using full wave simulation tools to minimize reflections. Six test fixtures are specific to the BTH/BSH series connector set and identified by part numbers PCB-106580_SIG_01B & C through PCB-106580_SIG_03 B&C. Calibration standards specific to the BTH/BSH series are located on the calibration boards PCB-106580_SIG_05. To keep trace lengths short, three different test board sets were required to access the necessary signal pins.

PCB-106580-SIG-XX Test Fixtures

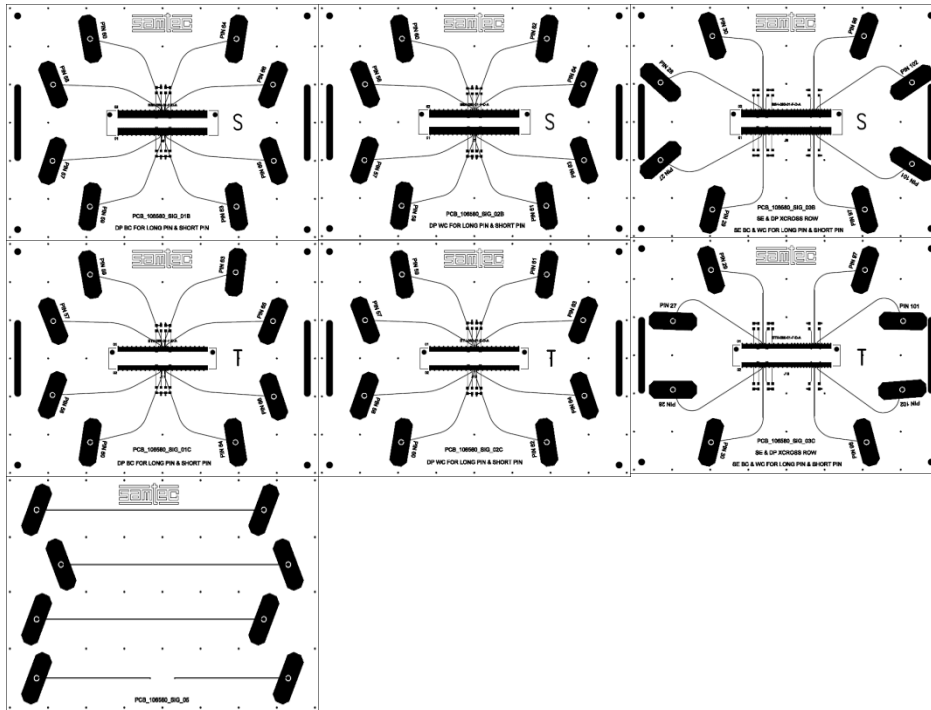
Shown below is a photograph of the one of the three test board sets.



Series: Basic Blade & Beam Header and Socket, Extended Life Product™
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PCB-106580-SIG-XX PCB Layout Panel

Artwork of the PCB design is shown below.



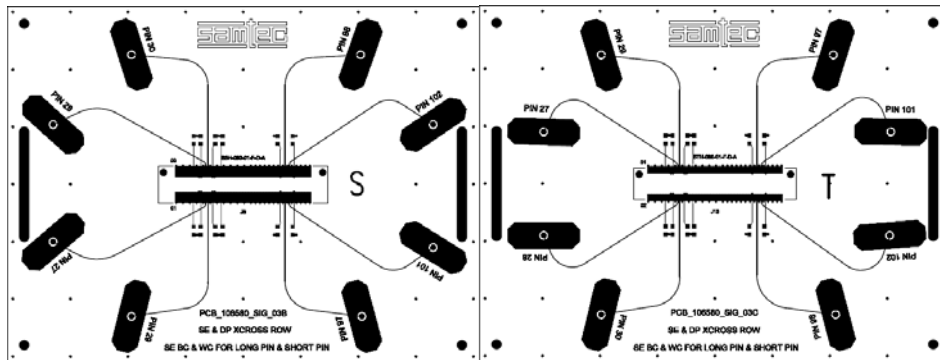
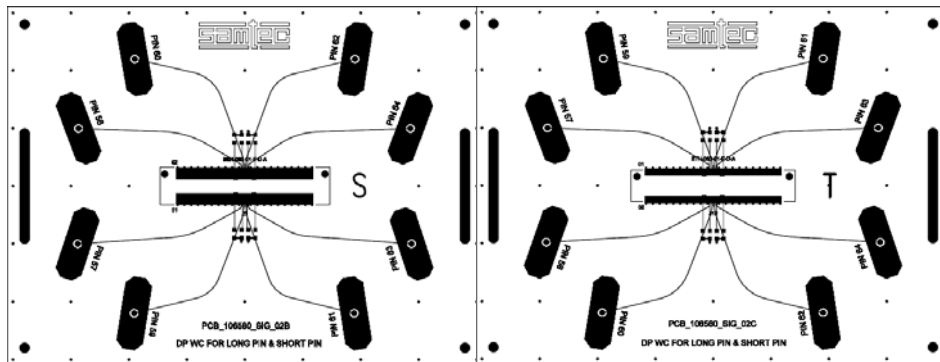
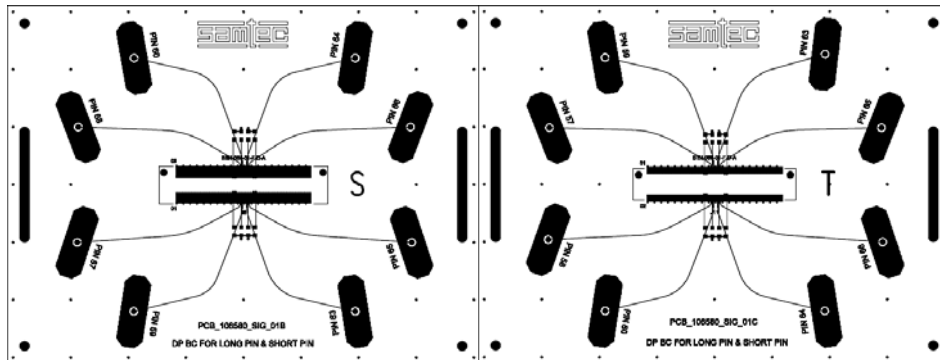
PCB Fixtures

The test fixtures used are as follows:

- PCB-106580-SIG-01B – BSH Vertical, Differential Best Case
- PCB-106580-SIG-01C – BTH Vertical, Differential Best Case
- PCB-106580-SIG-02B – BSH Vertical, Differential Worst Case
- PCB-106580-SIG-02C – BTH Vertical, Differential Worst Case
- PCB-106580-SIG-03B – BSH Vertical, Single Ended Best Case, Worst Case, Across-row; Differential Across-row
- PCB-106580-SIG-03C – BTH Vertical, Single Ended Best Case, Worst Case, Across-row; Differential Across-row
- PCB-106580-SIG-05 – Calibration Board

Series: Basic Blade & Beam Header and Socket, Extended Life Product™

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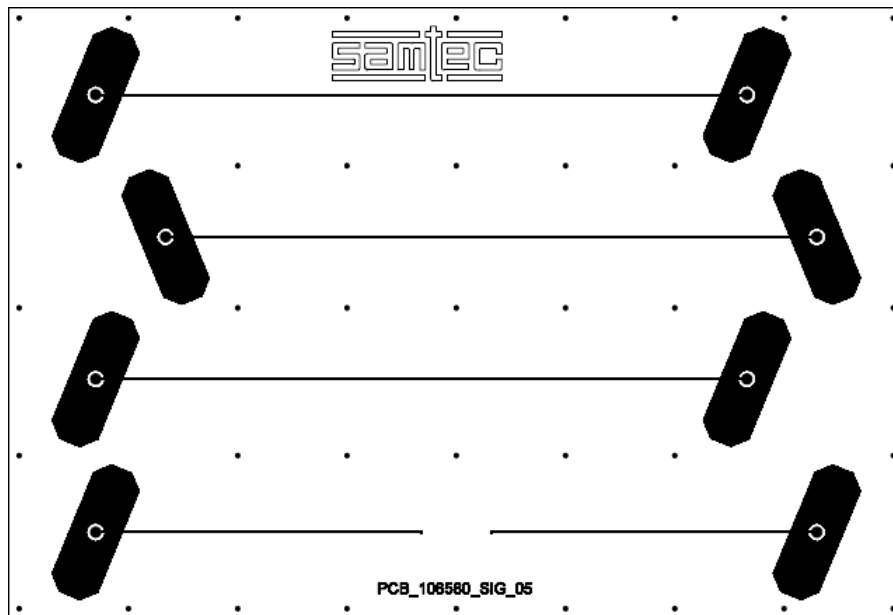


Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Calibration Board

Test fixture losses and test point reflections were removed from the data by use of AFR in PLTS. The calibration board is shown below. Prior to making any measurements, the calibration board is characterized to obtain parameters required to define the calibration kit. Once a cal kit is defined, calibration using the standards on the calibration board can be performed. Finally, the device can be measured and the test board effects are automatically removed.



Thru line – 2980 mils

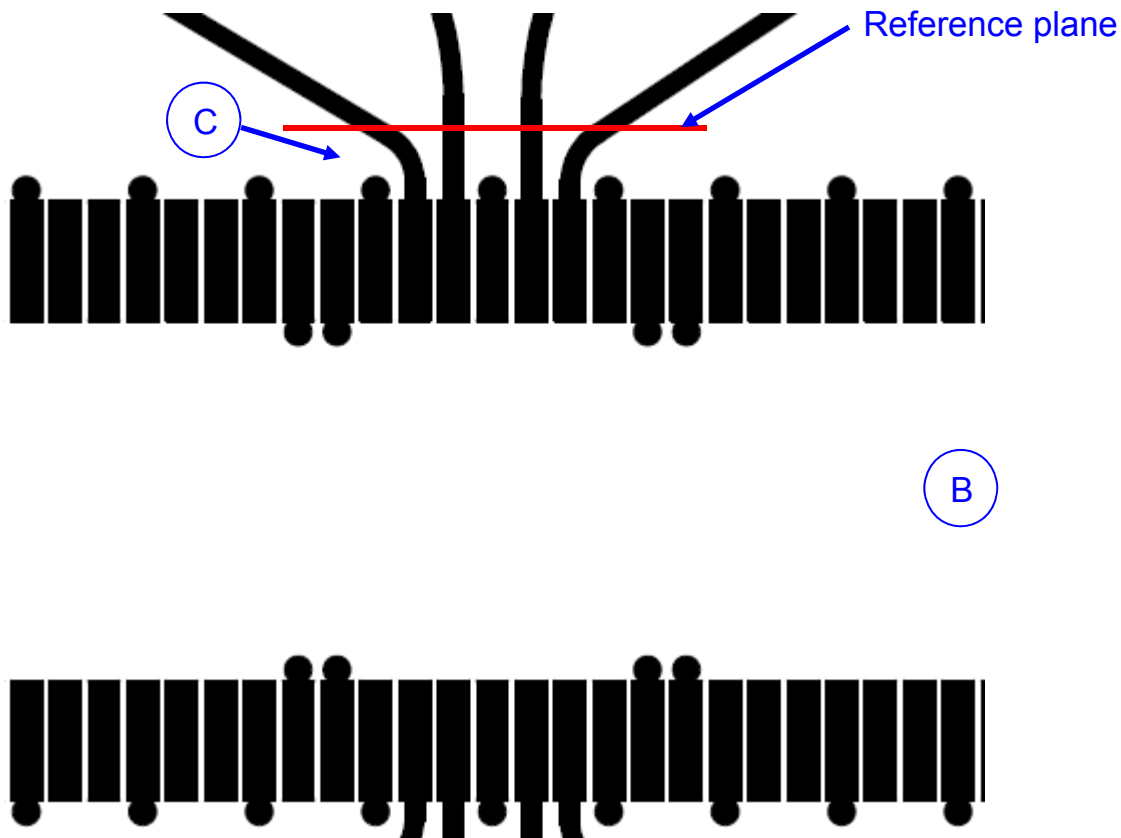
Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

All traces on the test boards are length matched to 1500 mils measured from the edge of the pad to the SMA. The calibration effectively removes 1490 mils of test board trace effects. This means that 10 mils of test board trace length effects are included in the both sides of test boards in the measurement. The S-Parameter measurement includes:

- A- The BTH/BSH Series connector set
- B- Test board vias, pads (footprint effects)
- C- 10 mils of 10.2 mil wide microstrip trace

The figure below shows the location of the reference plane.



Series: Basic Blade & Beam Header and Socket, Extended Life Product™
Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

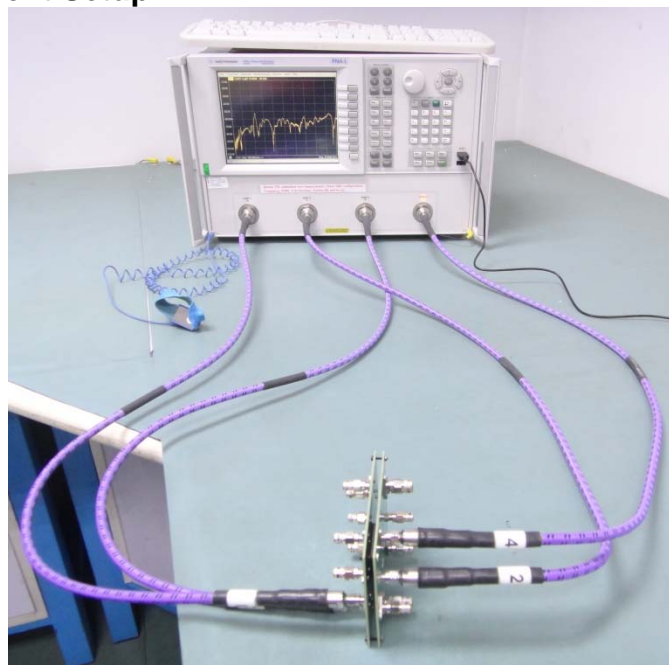
Appendix D – Test and Measurement Setup

For frequency domain measurements, the test instrument is the Agilent N5230C PNA-L network analyzer. Frequency domain data and graphs are obtained directly from the instrument. Post-processed time domain data and graphs are generated using convolution algorithms within Agilent ADS. The network analyzer is configured as follows:

Start Frequency – 300 KHz
Stop Frequency – 20 GHz
Number of points -1601
IFBW – 1 KHz

With these settings, the measurement time is approximately 20 seconds.

N5230C Measurement Setup



Test Instruments

<u>QTY</u>	<u>Description</u>
1	Agilent N5230C PNA-L Network Analyzer (300 KHz to 20 GHz)
1	Agilent N4433A ecal module (300 KHz to 20 GHz)

Test Cables & Adapters

<u>QTY</u>	<u>Description</u>
4	Gore OWD01D02039-4 (DC-50 GHz)

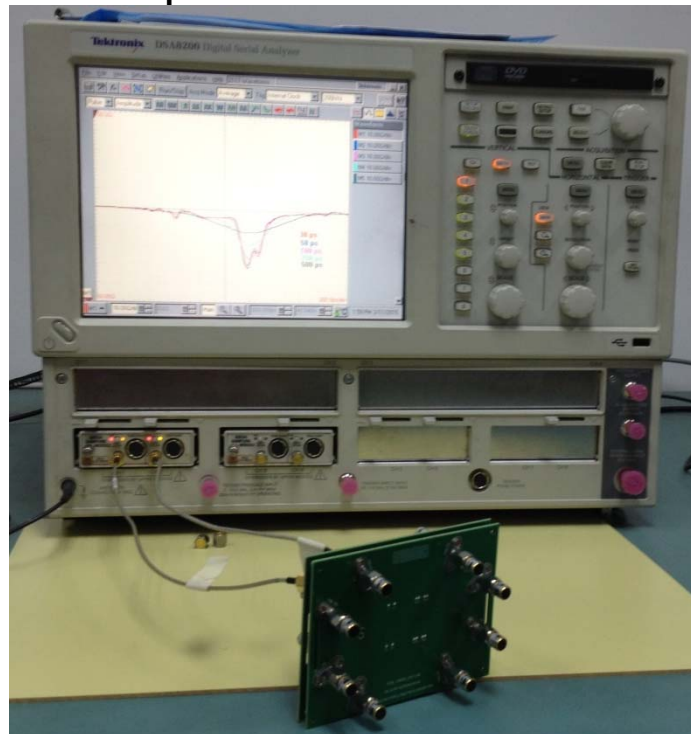
Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

For impedance measurements, the test instrument is the Tektronix DSA8200 Digital Serial Analyzer mainframe and 80E04 sampling module. The impedance data and profiles are obtained directly from the instrument. The Digital Analyzer is configured as follows:

	Single-Ended Signal	Differential Signal
Vertical Scale:	5 ohm / Div	10 ohm / Div
Offset:	Default / Scroll	Default / Scroll
Horizontal Scale:	200ps/ Div	200ps/ Div
Record Length:	4000	4000
Averages:	≥ 16	≥ 16

DSA8200 Measurement Setup



Test Instruments

<u>QTY</u>	<u>Description</u>
1	Tektronix DSA8200 Digital Serial Analyzer
2	Tektronix 80E04 Dual Channel 20 GHz TDR Sampling Module

Test Cables & Adapters

<u>QTY</u>	<u>Description</u>
4	Samtec RF405-01SP1-01SP1-0305 (DC-20 GHz)

Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Appendix E - Frequency and Time Domain Measurements

Frequency (S-Parameter) Domain Procedures

The quality of any data taken with a network analyzer is directly related to the quality of the calibration standards and the use of proper test procedures. For this reason, extreme care is taken in the design of the through calibration standards, the SI test boards, and the selection of the PCB vendor.

The measurement process begins with a measurement of the LRM calibration standards. A coaxial SOLT calibration is performed using an N4433A ecal module. This measurement is required in order to obtain precise values of the line standard offset delay and frequency bandwidths. Measurements of the reflect and 2x through line standard can be used to determine the maximum frequency for which the calibration standards are valid. For the BTH/BSH Series test boards, this is greater than 20 GHz.

From the LRM calibration standard measurements, a user defined calibration kit is developed and stored in the network analyzer. Calibration is then performed on all 4 ports following the calibration wizard within the Agilent N5230C. This calibration is saved and can be recalled at any time. Calibration takes roughly 30 minutes to perform.

Time Domain Procedures

Mathematically, Frequency Domain data can be transformed to obtain a Time Domain response. Perfect transformation requires Frequency Domain data from DC to infinity Hz. Fortunately, a very accurate Time Domain response can be obtained with bandwidth-limited data, such as measured with modern network analyzer.

The Time Domain responses were generated using Agilent ADS 2009 update 1. This tool has a transient convolution simulator, which can generate a Time Domain response directly from measured S-Parameters. An example of a similar methodology is provided in the Samtec Technical Note on domain transformation.

[http://www.samtec.com/Technical_Library/reference/articles/pdfs/tech-note_using-PLTS-for-time-domain-data_web.pdf](http://www.samtec.com/Technical_Library/reference/articles/pdfs/tech-note_using_PLTS-for-time-domain-data_web.pdf)

Propagation Delay (TDT)

The Propagation Delay is a measure of the Time Domain delay through the connector and footprint. A step pulse is applied to the touchstone model of the connector and the transmitted voltage is monitored. The same pulse is also applied to a reference channel with zero loss, and the Time Domain pulses are plotted on the same graph. The difference in time, measured at the 50% point of the step voltage is the propagation delay.

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Near-End Crosstalk (TDT) & Far End Crosstalk (TDT)

A step pulse is applied to the touchstone model of the connector and the coupled voltage is monitored. The amplitude of the peak-coupled voltage is recorded and reported as a percentage of the input pulse.

Impedance (TDR)

Measurements involving digital pulses are performed using either Time Domain Reflectometer (TDR) or Time Domain Transmission (TDT) methods. The TDR method is used for the impedance measurements in this report.

The signal line(s) of the SUT's is energized with a TDR pulse and the far-end of the energized signal line is terminated in the test systems characteristic impedance (e.g.; 50Ω or 100Ω terminations). By terminating the adjacent signal lines in the test systems characteristic impedance, the effects on the resultant impedance shape of the waveform is limited. The "best case" signal mapping was tested and is presented in this report.

Series: Basic Blade & Beam Header and Socket, Extended Life Product™

Description: 0.5mm (.0197") Pitch, 5mm (.197") Stack Height

Appendix F – Glossary of Terms

ADS – Advanced Design Systems

AFR – Automatic Fixture Removal

BC – Best Case crosstalk configuration

DUT – Device under test, term used for TDA IConnect & Propagation Delay waveforms

FD – Frequency domain

FEXT – Far-End Crosstalk

GSG – Ground–Signal–Ground; geometric configuration

GSSG - Ground–Signal–Signal–Ground; geometric configuration

HDV – High Density Vertical

NEXT – Near-End Crosstalk

OV – Optimal Vertical

OH – Optimal Horizontal

PCB – Printed Circuit Board

PPO – Pin Population Option

SE – Single-Ended

SI – Signal Integrity

SUT – System Under Test

S – Static (independent of PCB ground)

SOLT – acronym used to define Short, Open, Load & Thru Calibration Standards

TD – Time Domain

TDA – Time Domain Analysis

TDR – Time Domain Reflectometry

TDT – Time Domain Transmission

WC – Worst Case crosstalk configuration

Z – Impedance (expressed in ohms)